

WHAT IS CLAIMED IS:

1. A display apparatus, comprising:  
an insulating substrate;

5 a signal line for transmitting a signal to a  
pixel formed in a display area composed of pixels on  
the insulating substrate;

a driver integrated circuit (IC) mounted  
outside of the display area of the insulating  
10 substrate and electrically connected to the signal  
line; and

an inspection pad formed outside of the display  
area of the insulating substrate, electrically  
connected to the signal line, and covered with resin.

15 2. A display apparatus according to Claim 1,  
wherein the resin is selected from the group  
consisting of silicon, acryl, urethane, epoxy, and  
polyimide.

20 3. A display apparatus according to Claim 1,  
wherein the resin is an anisotropic conductive film.

25 4. A display apparatus according to Claim 1,  
further comprising:

a signal input pad formed outside of the display

area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC,

wherein the signal input pad and the inspection pad are covered with an anisotropic conductive film.

5  
5. A display apparatus according to Claim 1, further comprising:

10 a conductive extension line connecting the signal line and the driver IC to the inspection pad.

6. A display apparatus according to Claim 2, further comprising:

15 a conductive extension line connecting the signal line and the driver IC to the inspection pad.

7. A display apparatus according to Claim 3, further comprising:

20 a conductive extension line connecting the signal line and the driver IC to the inspection pad.

8. A display apparatus according to Claim 4, further comprising:

25 a conductive extension line connecting the signal line and the driver IC to the inspection pad.

9. A display apparatus according to Claim 4,  
further comprising:

a wiring substrate for inputting a signal from  
outside of the insulating substrate to the driver IC,

5 wherein the wiring substrate and the signal  
input pad on the insulating substrate are  
electrically connected by the anisotropic conductive  
film, and

10 the wiring substrate covers the signal input pad  
and the inspection pad with the anisotropic  
conductive film interposed therebetween.

10. A display apparatus according to Claim 9,  
wherein the wiring substrate is a flexible substrate.

15 11. A display apparatus according to Claim 4,  
wherein the inspection pad and the signal input pad  
are substantially aligned along near an edge of the  
insulating substrate.

20 12. A method of manufacturing a display  
apparatus, comprising steps of:

forming a signal line for transmitting a signal  
to a pixel formed in a display area on the insulating  
25 substrate;

implementing a driver integrated circuit (IC)

outside of the display area of the insulating substrate and electrically connecting the driver IC to the signal line;

forming an inspection pad outside of the display area of the insulating substrate and electrically connecting the inspection pad to the signal line;

forming a signal input pad outside of the display area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC; and

simultaneously covering the inspection pad and the signal input pad with an anisotropic conductive film.

13. A method of manufacturing a display apparatus, comprising steps of:

forming a signal line for transmitting a signal to a pixel formed in a display area on the insulating substrate;

implementing a driver integrated circuit (IC) outside of the display area of the insulating substrate and electrically connecting the driver IC to the signal line;

forming an IC signal pad at a position corresponding to a pad formed on the driver IC on the insulating substrate;

forming an inspection pad outside of the display area of the insulating substrate and electrically connecting the inspection pad to the signal line;

5        forming a signal input pad outside of the display area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC; and

10       simultaneously covering the inspection pad and the signal input pad with an anisotropic conductive film.